

## REMARKS

Claims 73-91 remain in the application for further prosecution. Claims 73, 78, 80, 83, 86, and 89 have been amended. No claims have been added or canceled.

### Allowable Subject Matter

Claims 73-91 are allowed. The application is in condition for allowance except for the formal matters addressed below.

### Specification Objection

The Examiner has requested that the current title be changed to be “clearly indicative of the invention to which the claims are directed,” suggesting, for example, “The method of manufacturing a leaser [sic] diode package.” In compliance with the Examiner’s request, the current title has been changed to “A method of manufacturing a laser diode package.”

### Claim Objections:

Claim 73 has been objected to because the claim element “said substrate” in line 6 allegedly lacks proper antecedent basis. Similar changes have been requested to claims 78, 80, 83, and 86. Specifically, the Examiner has suggested changing the element “said substrate” to “said electrically insulative substrate.” Claims 73, 78, 80, 83, and 86 have been amended to comply with the Examiner’s request.

Claim 73 has been further objected regarding the claim phrase “providing a heat sink having upper and lower portions, **said heat sink having a width that is approximately said heat sink width that is less than height.**” The Examiner has noted that the claim is “confusing because the width and the height comparison is not particularly claimed.” The Examiner has suggested to modify the claim phrase, for example, to the following claim phrase: “wherein said heat sink having height and width and wherein said width of said heat sink is approximately less than that of said height of said heat sink.”

It seems that the Examiner has misquoted claim 73, which includes the claim phrase “providing a heat sink having upper and lower portions, **said heat sink having a height and a heat sink width that is less than said height.**” Nevertheless, in accordance with the Examiner’s suggestion, claim 73 has been amended to include the claim phrase “said heat sink having a heat sink height and a heat sink width, said heat sink width being less than said heat sink height.”

Claim 73 has also been objected to regarding the claim phrase “providing an electrically insulative substrate, **said substrate having a width that approximately said heat sink width.**” The Examiner has suggested to modify the claim phrase, for example, to the following claim phrase: “wherein said electrically insulating substrate having a width that is approximately equal to said width of said heat sink.” In accordance with the Examiner’s suggestion, claim 73 has been amended to include the claim phrase “said electrically insulative substrate having a substrate width that is approximately equal to said heat sink width.”

### **Conclusion**

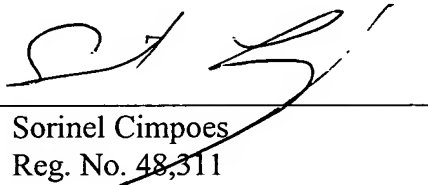
It is the Applicant’s belief that all of the claims are now in condition for allowance and action towards that effect is respectfully requested.

If there are any matters which may be resolved or clarified through a telephone interview, the Examiner is requested to contact the undersigned attorney at the number indicated.

Respectfully submitted,

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By



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